



Session Title:	[WeG3] Frontier Metrology and Modeling V
Session Date:	November 13 (Wed.), 2024
Session Time:	16:10-17:45
Session Room:	Room G (Meeting Room, 5F, Grand Josun Busan)
Session Chair:	Dr. Byoung-Ho Lee (Hitachi High-Tech, Japan)

[WeG3-1] [Invited]

16:10-16:40

MI's New Challenges and Approaches

ByoungHo Lee (Hitachi High-tech, Japan)

[WeG3-2]

16:40-17:00

Multi-Spectrum and In-FAB Data Based Deep Learning Modeling for Early Prediction of Electrical Characteristics

Min Seok Kim, Yeonjeong Kim, Taeshin Kwak, Kyunghoon Lee, Jongchul Kim, Younghoon Sohn, Yongdeok Jeong, and Hyung Keun Yoo (Samsung Electronics Co., Ltd., Korea)

[WeG3-3]

17:00-17:20

AI Image Enhancement for High Speed On-Cell Overlay

Hyeon Bo Shim, Souk Kim, Younghoon Sohn, and Yongdeok Jeong (Samsung Electronics Co., Ltd., Korea)

[WeG3-4] [Invited]

17:20-17:45

***In situ* and Operando Transmission Electron Microscopy Study of Compound Semiconductor and Packaging Materials**

Young Heon Kim (Chungnam Nat'l Univ., Korea)